METHOD FOR DETACHING A SEMICONDUCTOR CHIP FROM A FOIL AND APPARATUS FOR MOUNTING SEMICONDUCTOR CHIPS

ABSTRACT

The detachment of a semiconductor chip (1) from a foil (4) and picking the semiconductor chip (1) from the foil (4) takes place with the support of a chip ejector (6), that has a ramp (16), the surface (17) of which is formed concave and ends at a stripping edge (18) projecting from the surface (9) of the chip ejector (6), and a support area (13) with grooves (12) arranged next to the stripping edge (18). Vacuum can be applied to the grooves (12). The detachment and picking of the semiconductor chip (1) from the foil (4) takes place in that the wafer table (5) is shifted relative to the chip ejector (6) in order to pull the foil (4) over the stripping edge (18) protruding from the surface (9) of the chip ejector (6), whereby the semiconductor chip (1) temporarily detaches itself at least partially from the foil (4) and lands on the foil (4) above the support area (13), and in that the chip gripper (7) picks the semiconductor chip (1) presented on the support area (13).

(Fig. 3)